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**Part Number:** [73780-1123](#)  
**Status:** **Active**  
**Overview:** [HDM®](#)  
**Description:** 2.00mm Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 13.00mm, Pin Length 2.00mm, Solder Tail

**Documents:**

[3D Model](#) [Test Summary TS-73670-990 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Product Specification PS-73780-999 \(PDF\)](#)

**General**

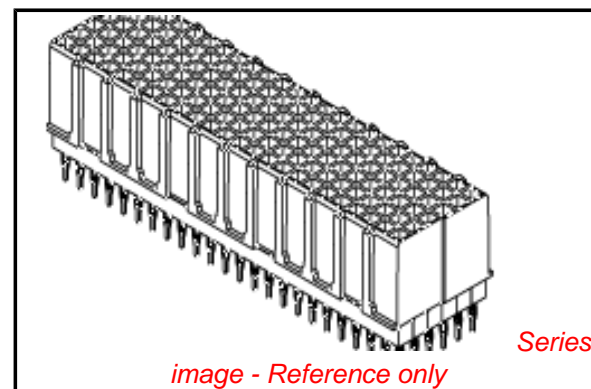
Product Family	Backplane Connectors
Series	<a href="#">73780</a>
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	<a href="#">HDM®</a>
Product Name	HDM®
Style	N/A
UPC	800755029246

**Physical**

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	20.030/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	2.00mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

**Electrical**

Current - Maximum per Contact	15A, 1A
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**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC  
Contains SVHC: No**  
**Low-Halogen Status  
Low-Halogen**

**China RoHS**



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 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73780Series](#)

**Mates With**

HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

#### **Solder Process Data**

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

#### **Material Info**

#### **Reference - Drawing Numbers**

Product Specification	PS-73780-999
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990

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